

HENKEL SOLUTIONS FOR AUTOMOTIVE ELECTRONICS COMPONENTS

BERGQUIST® GAP FILLER TGF 4400LVO

Next Generation, 2-component, low volatile outgassing silicone-based gap filler

Features & Benefits

- 2-component solution based on low volatile silicone technology
- Thin bold line achievable for thermal resistance optimization by design
- Balanced working time (90 minutes) and cure profile < 12 hour at room temperature
- Thermal conductivity 4.4 W/(m.K) typical
- Fast and robust dispensing
- High reliability under severe thermal load

Sustainability Value

- Long working time increases customer process window, reducing scrap at the production line
- Low concentration of volatile siloxanes

Leverage Henkel's broad technology portfolio and application know-how to strengthen your automotive electronics applications.



Henkel Adhesive Technologies







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Next Generation, 2-component, low volatile outgassing silicone-based gap filler

BENEFITS

- Low volatile silicone with limited outgassing
- Suited for thin bond-line enabling:
 - Lower overall thermal resistance
 - Design flexibility for a wide range of gaps
- Excellent vertical gap stability for long-term reliability and performance
- Ease of dispensing with high shot consistency for high throughput manufacturing
- Excellent wet-out for lower thermal impedance

TYPICAL APPLICATIONS

- Automotive control units, ADAS camera, LiDAR data modules and displays
- Applications in automotive and industrial electronics requiring fast processing and high reliability





AVAILABLE CONFIGRATIONS

- 50 cc, 400 cc & 660 cc cartridges
- 1200 cc semco kits
- 20 L-Pail pail kits

Reach out to our experts to partner up for automotive electronics in automotive and industrial electronics.

CONTACT US TO LEARN MORE

Europe Germany Henkel AG & Co. KGaA (Headquarters) Henkelstraße 67, 40589 Düsseldorf

Asia-Pacific China Henkel (China) Co., Ltd. No. 928 Zhangheng Road, Pudong New District 201203 Shanghai



U.S.A. Henkel Corporation Madison Heights, 32100 Stephenson Highway Madison Heights, MI 48071



www.henkel-adhesives.com

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Product Properties

Technology	Silicone (2 C)
Thermal Conductivity, ASTM D5470	4.4 W/(m.K) typical
Shore Hardness (00)	90
Flow Rate (EFD 30 cc, 90 psi)	Part A: 1.0 cc/sec; Part B: 1.2 cc/sec
Cure	Room temperature or heat*
Working Time	90 min at 25°C

* For more guidelines on best dispensing practices, please contact Henkel's Application Engineering Team